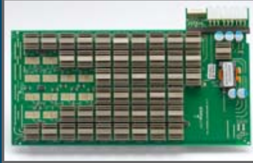
Advanced Packaging Update:

Market and Technology Trends

Vol. 4-0218



This issue of the Advanced Packaging Update features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The CSP market is divided into laminate substrates, leadframe (QFN), and stacked die. Unit growth projections for package-on-package (PoP) are provided. Estimates of the market for each package type are based on input from captive as well as merchant assembly operations. Drivers for growth in each segment are discussed and the impact of cryptocurrency is analyzed. A special section is devoted to 5G and the requirements for packages. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry.

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Annual subscription – $5,100 (4 issues)
Single issue – $2,500
Corporate license – $8,750

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